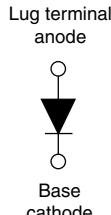


HEXFRED®

Ultrafast Soft Recovery Diode, 275 A


HALF-PAK (D-67)


FEATURES

- Very low Q_{rr} and t_{rr}
- Designed and qualified for industrial level
- UL approved file E222165 
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced snubbing

DESCRIPTION

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dI/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

PRIMARY CHARACTERISTICS	
I_F (maximum)	275 A
V_R	400 V
$I_{F(DC)}$ at T_C	138 A at 100 °C
Package	HALF-PAK (D-67)
Circuit configuration	Single diode

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Cathode to anode voltage	V_R			400	V
Continuous forward current	I_F	$T_C = 25^\circ\text{C}$		275	A
		$T_C = 100^\circ\text{C}$		138	
Single pulse forward current	I_{FSM}	Limited by junction temperature		900	
Non-repetitive avalanche energy	E_{AS}	$L = 100 \mu\text{H}$, duty cycle limited by maximum T_J		1.4	mJ
Maximum power dissipation	P_D	$T_C = 25^\circ\text{C}$		463	W
		$T_C = 100^\circ\text{C}$		185	
Operating junction and storage temperature range	T_J , T_{Stg}			-55 to +150	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 100 \mu\text{A}$		400	-	-	V
Maximum forward voltage	V_{FM}	$I_F = 135 \text{ A}$	See fig. 1	-	1.06	1.65	
		$I_F = 270 \text{ A}$		-	1.2	2.0	
		$I_F = 135 \text{ A}$, $T_J = 125^\circ\text{C}$		-	0.96	1.58	
Maximum reverse leakage current	I_{RM}	$T_J = 125^\circ\text{C}$, $V_R = 400 \text{ V}$	See fig. 2	-	-	3	mA
Junction capacitance	C_T	$V_R = 200 \text{ V}$	See fig. 3	-	280	380	pF
Series inductance	L_S	From top of terminal hole to mounting plane		-	6.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5	t_{rr}	$T_J = 25^\circ\text{C}$	$I_F = 135\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 200\text{ V}$	-	77	120	ns
		$T_J = 125^\circ\text{C}$		-	280	440	
Peak recovery current See fig. 6	I_{RRM}	$T_J = 25^\circ\text{C}$	$V_R = 200\text{ V}$	-	7.5	14	A
		$T_J = 125^\circ\text{C}$		-	15	30	
Reverse recovery charge See fig. 7	Q_{rr}	$T_J = 25^\circ\text{C}$	$V_R = 200\text{ V}$	-	150	780	nC
		$T_J = 125^\circ\text{C}$		-	2800	6300	
Peak rate of recovery current See fig. 8	$dI_{(rec)M}/dt$	$T_J = 25^\circ\text{C}$	$V_R = 200\text{ V}$	-	350	-	$\text{A}/\mu\text{s}$
		$T_J = 125^\circ\text{C}$		-	300	-	

THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J , T_{Stg}		-55 to +150	°C
Maximum thermal resistance, junction to case	R_{thJC}	DC operation See fig. 4	0.27	°C/W
Typical thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	0.05	
Approximate weight			30	g
			1.06	oz.
Mounting torque	minimum		3 (26.5)	$\text{N} \cdot \text{m}$ (lbf · in)
	maximum		4 (35.4)	
Terminal torque	minimum		3.4 (30)	
	maximum		5 (44.2)	
Case style		HALF-PAK (D-67)		

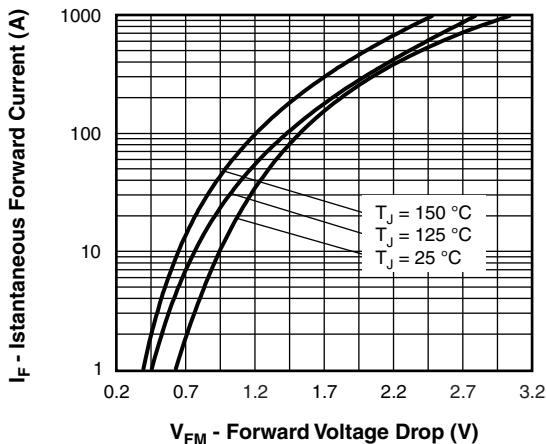


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

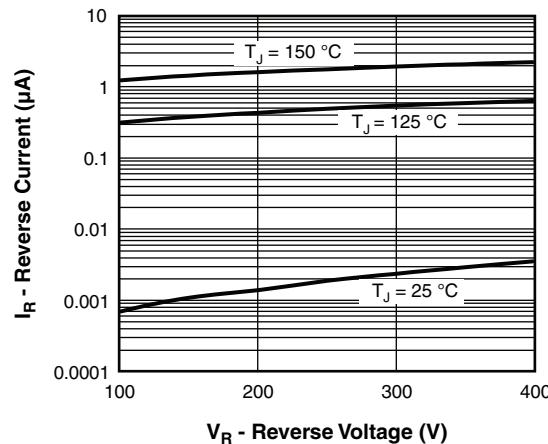


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

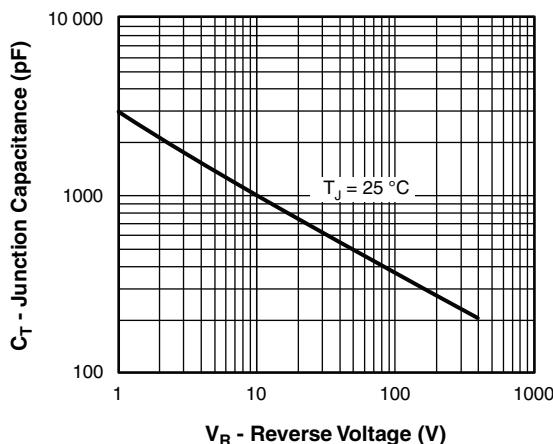


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

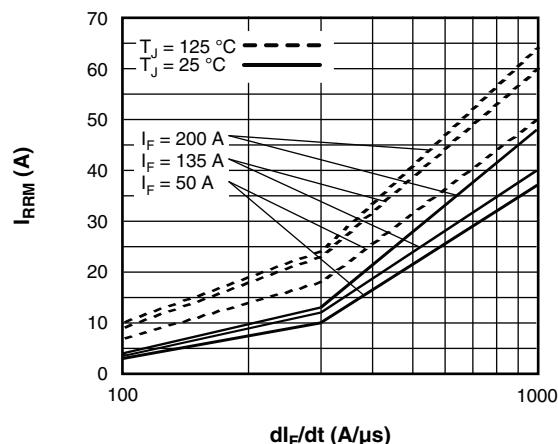


Fig. 6 - Typical Recovery Current vs. dI_F/dt

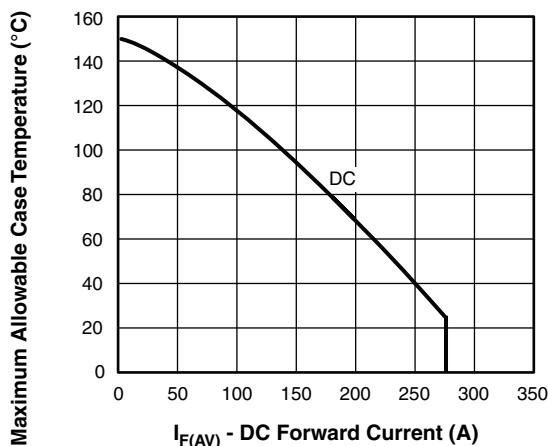


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current

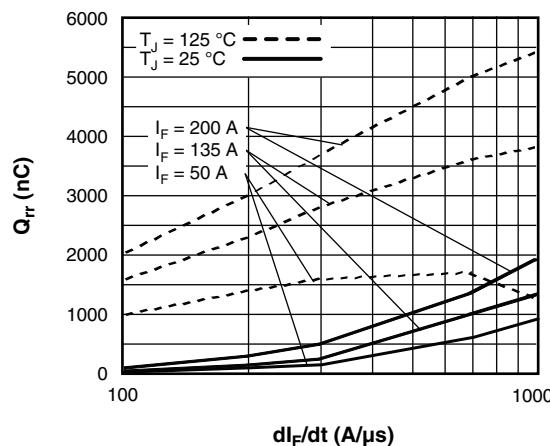


Fig. 7 - Typical Stored Charge vs. dI_F/dt

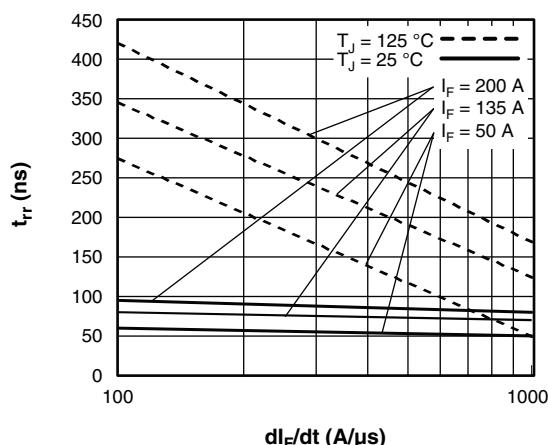


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt

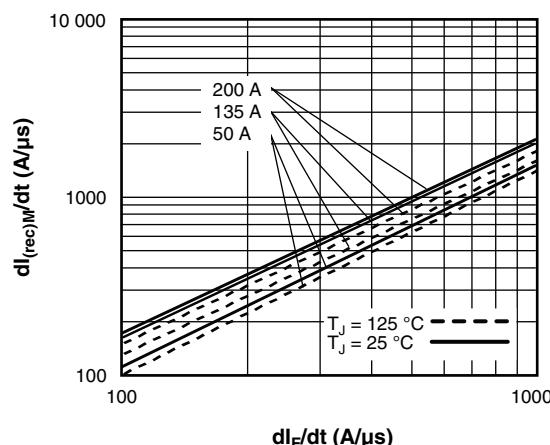


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

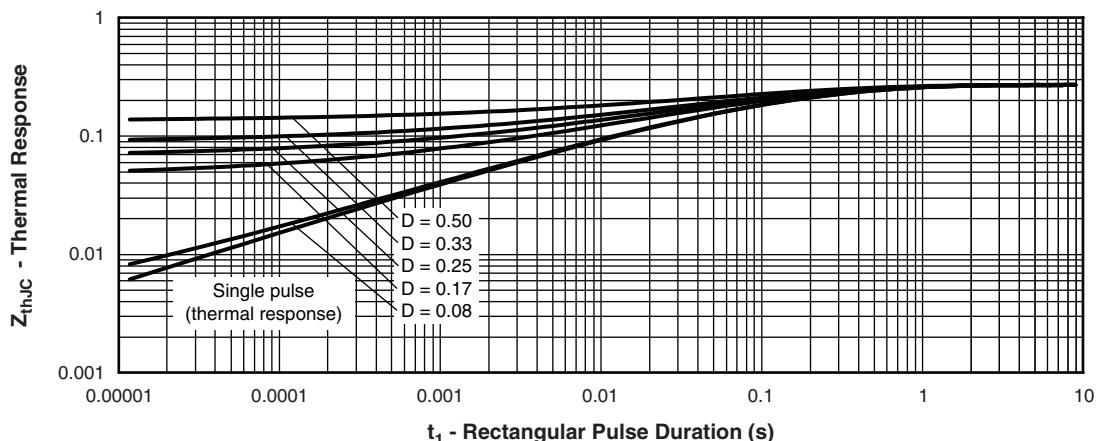


Fig. 9 - Maximum Thermal Impedance Z_{thJC} Characteristics

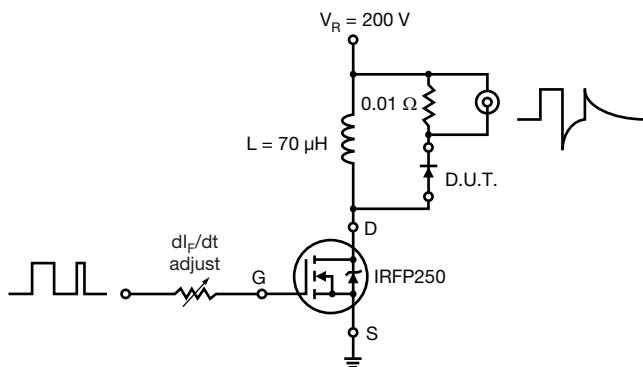
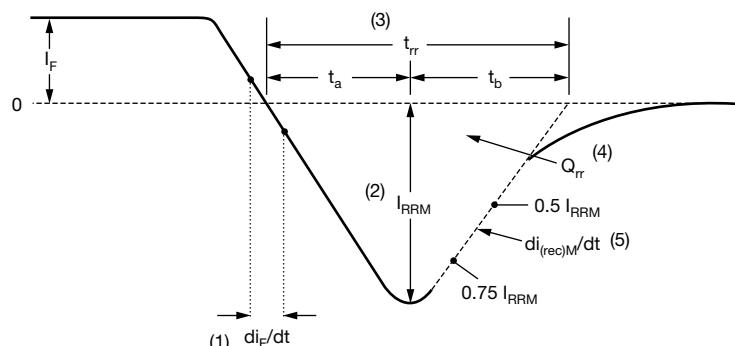


Fig. 10 - Reverse Recovery Parameter Test Circuit



(1) di_F/dt - rate of change of current through zero crossing

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

(2) I_{RRM} - peak reverse recovery current

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions

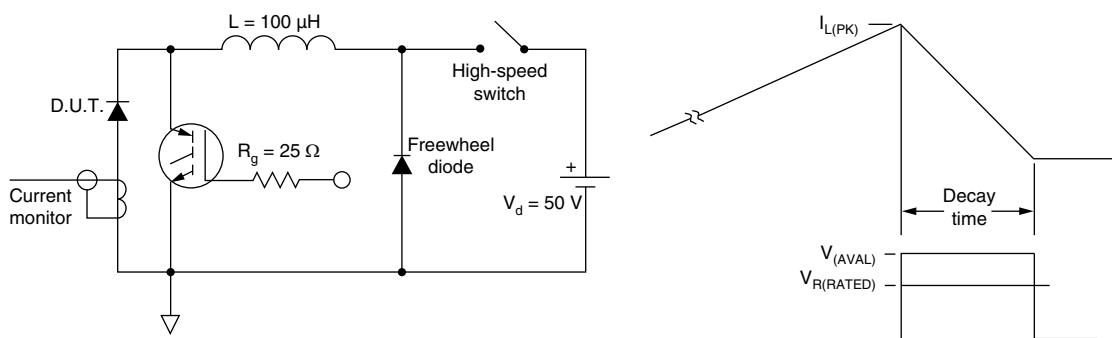


Fig. 12 - Avalanche Test Circuit and Waveforms

ORDERING INFORMATION TABLE

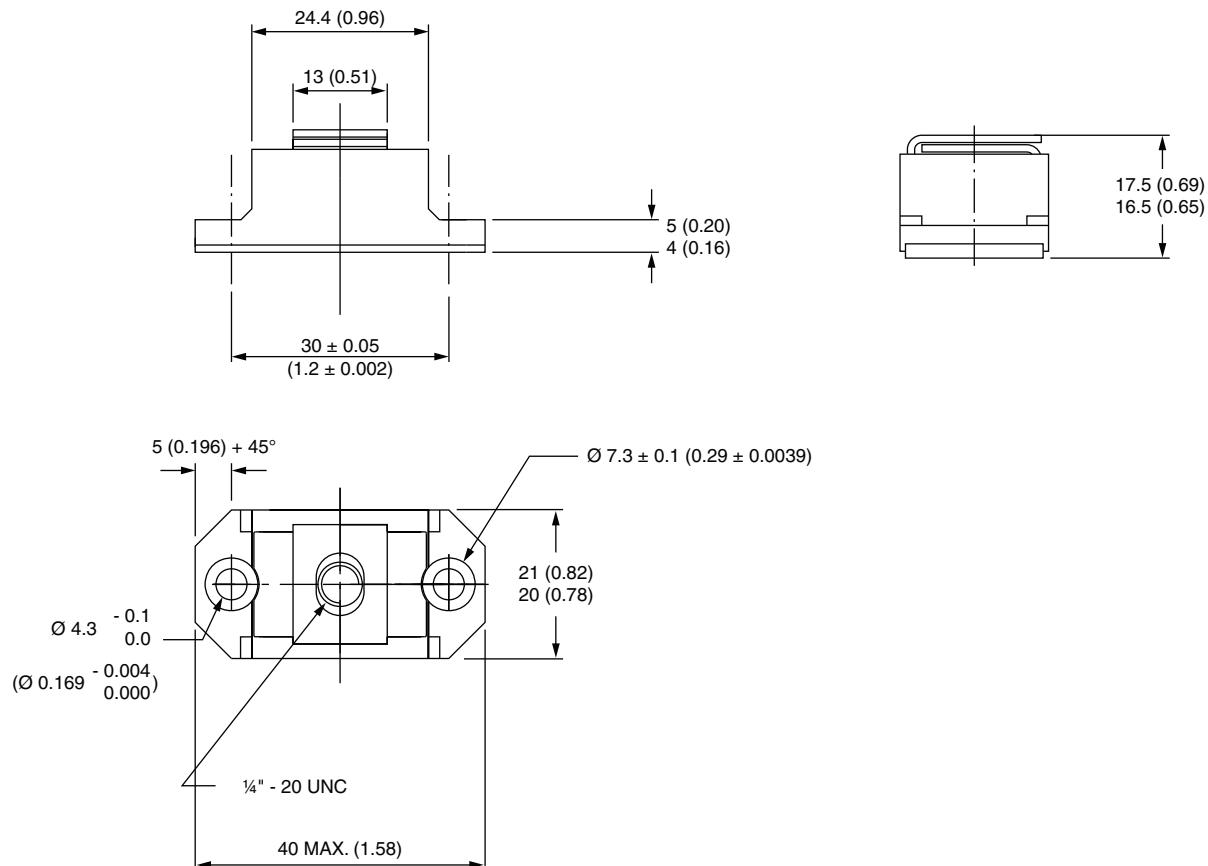
Device code	VS-	HFA	135	N	H	40	PbF
	1	2	3	4	5	6	7

- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Average current rating
- 4** - N = not isolated
- 5** - H = HALF-PAK (D-67)
- 6** - Voltage rating (400 V)
- 7** - Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95020

D-67 HALF-PAK

DIMENSIONS in millimeters (inches)



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